TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

2SK2382

Switching Regulator, DC-DC Converter and Motor Drive Applications

• Low drain–source ON resistance : RDS (ON) = 0.13 Ω (typ.)

• High forward transfer admittance $|Y_{fs}| = 17 \text{ S (typ.)}$

• Low leakage current : $IDSS = 100 \mu A \text{ (max) (VDS} = 200 \text{ V)}$

• Enhancement-mode : $V_{th} = 1.5 \sim 3.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	200	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	200	V	
Gate-source voltage		V_{GSS}	±20	٧	
Drain current	DC (Note 1)	I _D	15	Α	
	Pulse (Note 1)	I_{DP}	45	Α	
Drain power dissipatio	n (Tc = 25°C)	P_{D}	45	W	
Single pulse avalanche	e energy (Note 2)	E _{AS}	166	mJ	
Avalanche current		I _{AR}	15	Α	
Repetitive avalanche	energy (Note 3)	E _{AR}	4.5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.78	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: $V_{DD} = 50 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 1.2 mH, $R_G = 25 \Omega$, $I_{AR} = 15 \text{ A}$

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.

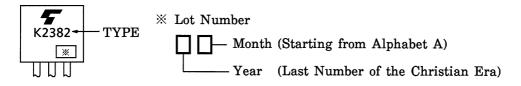
Electrical Characteristics (Ta = 25°C)

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	200	_	_	V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	1.5	_	3.5	V
Drain-source O	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 10 A	_	0.13	0.18	Ω
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 10 A	10	17	_	S
Input capacitano	e	C _{iss}		_	2000	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		200	_	pF
Output capacitance		C _{oss}			600	_	
Switching time	Rise time	t _r	$V_{GS} = 10V$ $V_{GS} = 100V$ $V_{OUT} = 100V$	_	35	_	
	Turn-on time	t _{on}		_	50	_	20
	Fall time	t _f		_	10		ns
	Turn-off time	t _{off}	$V_{DD} = 100V$ Duty $\leq 1\%$, $t_{W} = 10 \mu s$	_	66	l	
Total gate charge (Gate-source plus gate-drain)		Q_{g}	V _{DD} ≈ 100 V, V _{GS} = 10 V, I _D = 15 A		40	_	nC
Gate-source charge		Q_{gs}			25	_	
Gate-drain ("miller") charge		Q _{gd}			15	_	

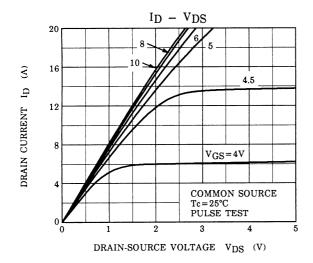
Source-Drain Ratings and Characteristics (Ta = 25°C)

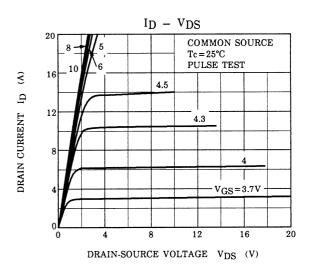
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	15	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	45	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 15 A, V _{GS} = 0 V	_	_	-2.0	V
Reverse recovery time	t _{rr}	I _{DR} = 15 A, V _{GS} = 0 V	1	180		ns
Reverse recovered charge	Q _{rr}	dI _{DR} / dt = 100 A / μs	_	1.13	_	μC

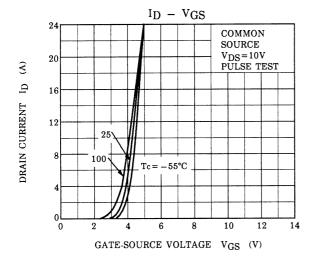
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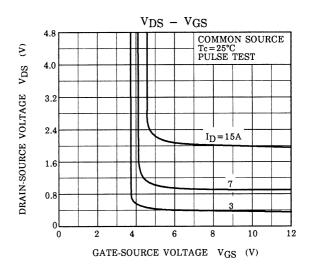


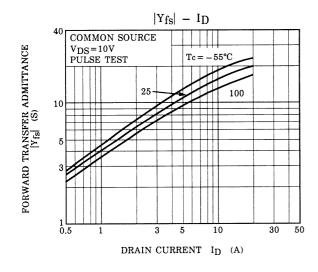
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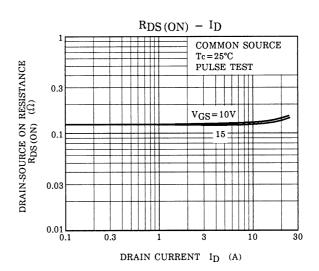




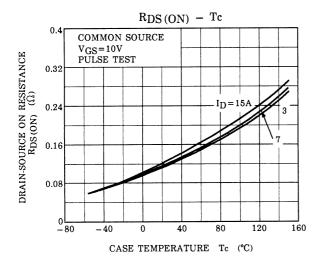


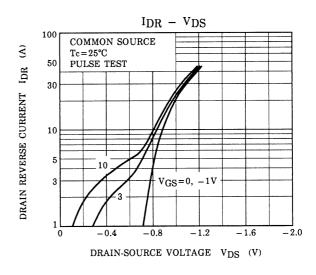


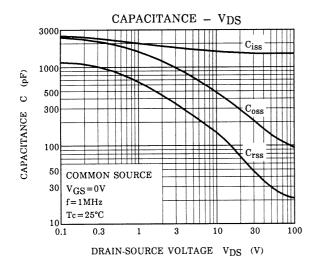


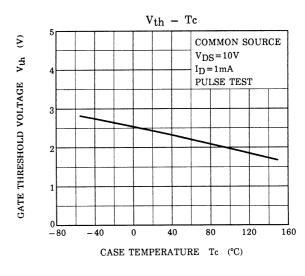


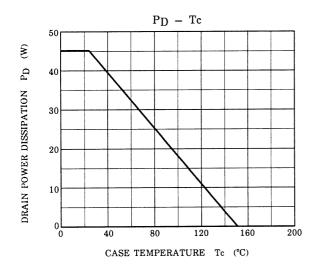
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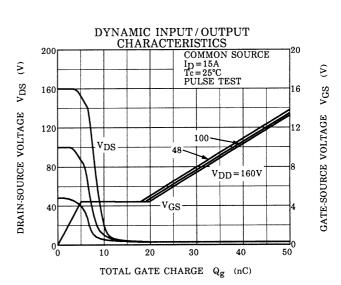




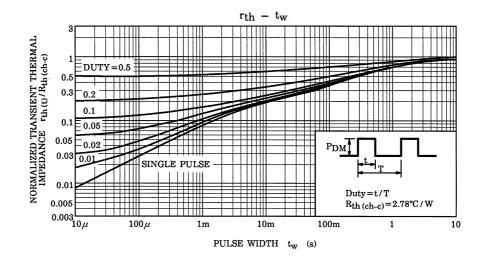


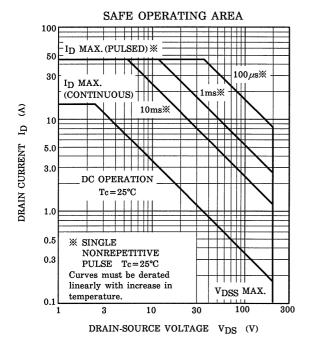


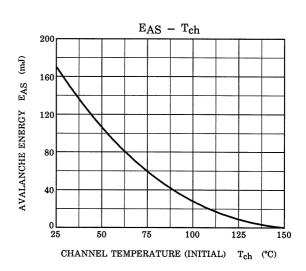


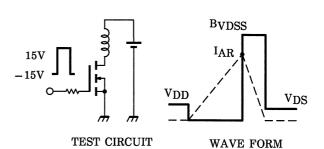


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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 50~V,~L = 1.2~mH \end{aligned} \qquad EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B^2}{BVDS}\right) \cdot \frac{1}{2} \cdot \frac{B^2}{BVDS} \cdot \frac{$$

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